

Initial Product/Process Change Notification

Document #:IPCN24082X Issue Date:18 May 2021

Title of Change:	LQFN 6X6 NCP3232NMNTXG, NCP3235MNTXG, NCP3233MNTXG, NCP3230MNTXG, NCP5369MNR2G, NCP5369MNTWG, NCP5369NMNTXG Change in Bond Wire from 1.3mil Gold to 1.3mil Palladium-Coated Copper Wire		
Proposed First Ship date:	25 Sep 2021 or earlier if approved by customer		
Contact Information:	Contact your local ON Semiconductor Sales Office or Wayne.Cheng@onsemi.com		
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or <pcn.samples@onsemi.com>. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.</pcn.samples@onsemi.com>		
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < PCN.Support@onsemi.com>		
Marking of Parts/ Traceability of Change:	The affected products will be identified with date code		
Change Category:	Assembly Change		
Change Sub-Category(s):	Material Change		
Sites Affected:			
ON Semiconductor Sites		External Foundry/Subcon Sites	
ON Semiconductor Seremban, Malaysia		None	

Description and Purpose:

LQFN 6X6 NCP3232NMNTXG, NCP3235MNTXG, NCP3233MNTXG, NCP3230MNTXG, NCP5369MNR2G, NCP5369MNTWG, NCP5369NMNTXG Change in Bond Wire from 1.3mil Gold to 1.3mil Palladium-Coated Copper Wire.

	Before Change Description	After Change Description	
Bond Wire	1.3mil Gold Wire	1.3mil Pd-Coated Copper Wire	
	(Part # B50607A083)	(Part # N40363E016)	

TEM001790 Rev. D Page 1 of 2



Initial Product/Process Change Notification

Document #:IPCN24082X Issue Date:18 May 2021

Qualification Plan:

QV DEVICE NAME: NCP3232NMNTXG

RMS: <u>072276</u>

PACKAGE: QFN 6x6 40L

Test	Specification	Condition	Interval
HTSL	JESD22-A103	Ta= 150°C	1008 hrs
TC	JESD22-A104	Ta= -65°C to +150°C	1000 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL 3 @ 260 °C	
SAT		Compare for Delamination before and after PC	
SD	JSTD002	Ta = 245C, 5 sec	

Estimated date for qualification completion: 1 June 2021

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
NCP5369NMNTXG	NCP3232NMNTXG
NCP5369MNTWG	NCP3232NMNTXG
NCP5369MNR2G	NCP3232NMNTXG
NCP3230MNTXG	NCP3232NMNTXG
NCP3233MNTXG	NCP3232NMNTXG
NCP3235MNTXG	NCP3232NMNTXG
NCP3232NMNTXG	NCP3232NMNTXG

TEM001790 Rev. D Page 2 of 2